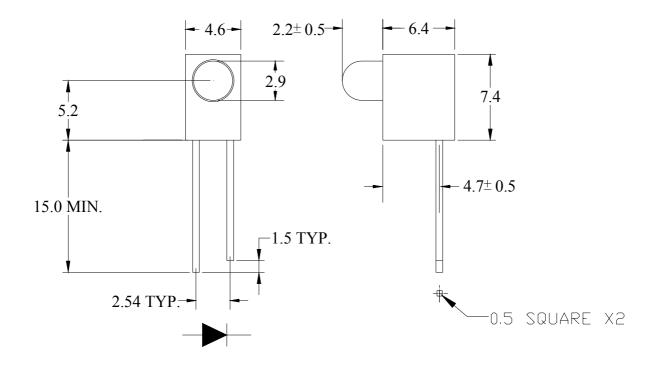
## **SPECIFICATION**

*PART NO.*: LT631Y-H102 2.9mm ROUND LED LAMP WITH HOLDER



Approved by	Checked by	Prepared by		
SAN	Sunny	Angel		

## **Package Dimensions**



#### Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is  $\pm 0.25$ mm unless otherwise noted.
- 3. The color of holder: Black.

## **Description**

Part No.	LED Chip			
	Material	Emitting Color	Description	
LT631Y-H102	GaAsP/GaP	Yellow	Yellow Diffused	

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## **Absolute Maximum Ratings at Ta=25 ℃**

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	78	mW
Reverse Voltage	VR	5	V
D.C. Forward Current	If	30	mA
Peak Current(1/10Duty duty,0.1ms Pulse Width.)	If(Peak)	100	mA
Operating Temperature Range	Topr.	-25 to +85	$^{\circ}\!\mathbb{C}$
Storage Temperature Range	Tstg.	-40 to +100	$^{\circ}\!\mathbb{C}$

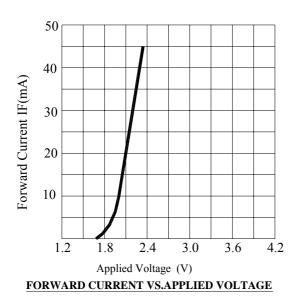
## **Electrical and Optical Characteristics:**

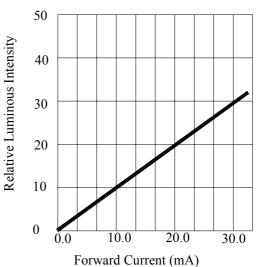
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity	Iv	If=20mA	12.0	20.0		mcd
Forward Voltage	Vf	If=20mA		2.1	2.6	V
Peak Wavelength	λΡ	If=20mA		585		nm
Dominant Wavelength	λD	If=20mA		590		nm
Reverse Current	Ir	Vr=5V			100	μΑ
Viewing Angle	2 0 1/2	If=20mA		55		deg
Spectrum Line Halfwidth	Δλ	If=20mA		35		nm

NOTE: THE DATAS COME FROM THE SPEC. OF LT6331-41

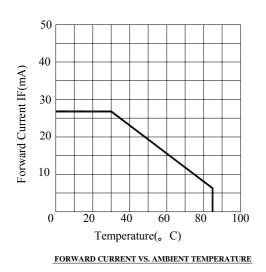
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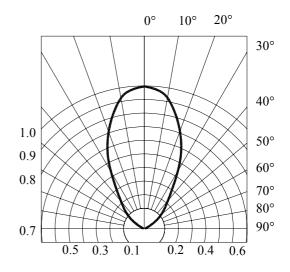
# Typical Electrical/Optical Characteristic Curves (25°C Ambient Temperature Unless Otherwise Noted)





FORWARD CURRENT VS. LUMINOUS INTENSITY





RADIATION DIAGRAM

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### **Precautions in Use:**

### Storage

Recommend storage environment

Temperature:  $5 \sim 30$ 

Soldering

### **Reflow Soldering**

Recommend use of upper and lower heater type reflow furnace.

300°C Max for up to 5 seconds.

Pre-heat is 150°C Max for up to 2 minutes Max.

In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

### **Manual Iron Soldering** (NOT RECOMMENDED)

Use SN60 solder of solder with silver content.

Use 25W soldering iron at 300°C Max for 5 seconds or less.

Must not touch top resin portion of lamp by heated soldering iron.

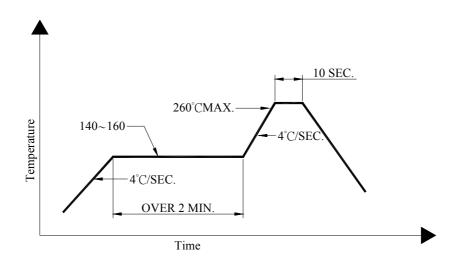
### Cleaning

Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

Avoid using organic solvent.

Recommend ultrasonic method 300W Max.

## Reflow Temp/Time:



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